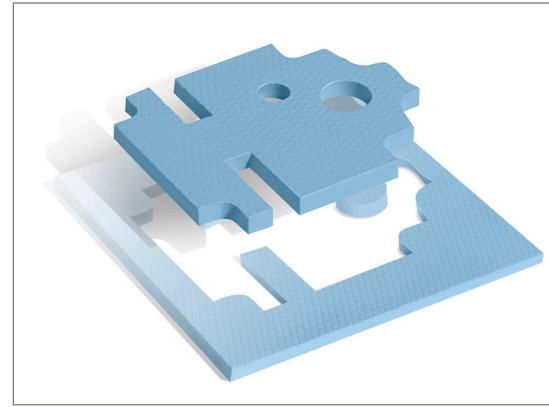


THERM-A-GAP™ PAD 30

3.2 W/m-K THERMALLY CONDUCTIVE GAP FILLER PAD

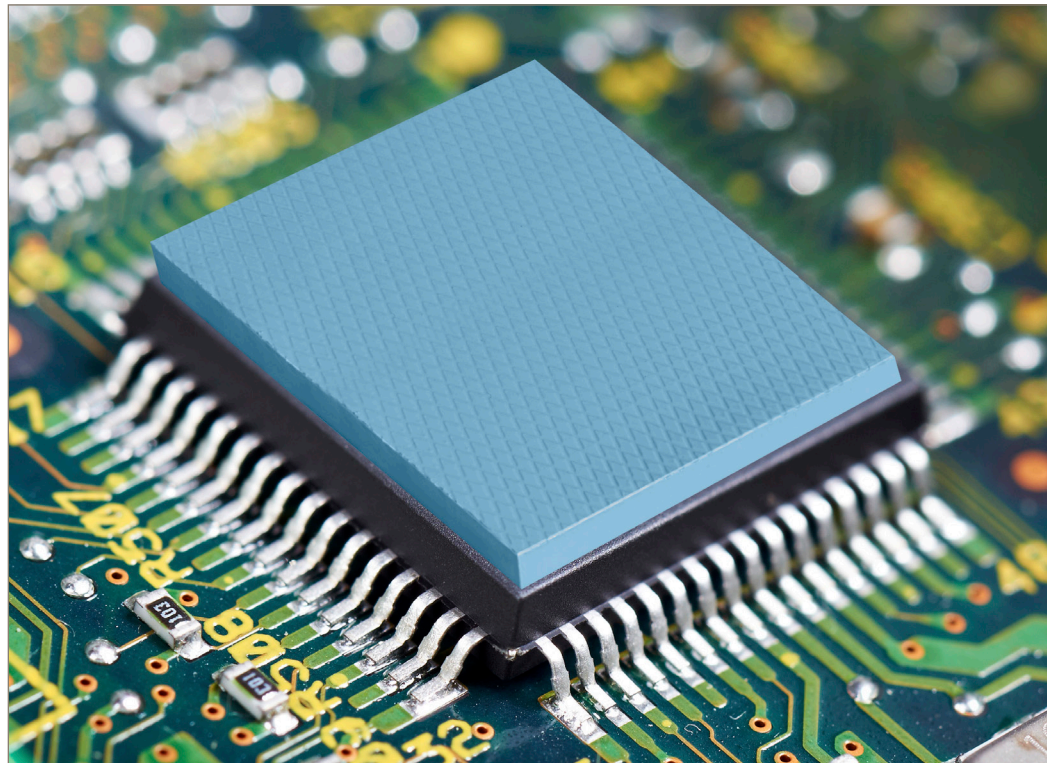


Customer Value Proposition:

Parker Chomerics THERM-A-GAP™ PAD 30 is a thermally conductive gap filler pad with 3.2 W/m-K thermal conductivity.

THERM-A-GAP PAD 30 offers the compelling combination of both excellent thermal performance and conformability, along with the lowest outgassing to provide an effective thermal interface between heat sinks and electronic devices where there are uneven surfaces, air gaps and rough surface textures.

THERM-A-GAP PAD 30 has been specifically formulated to conform to surface irregularities and adhere to a wide range of component shapes and sizes.



Product Features:

- 3.2 W/m-K thermal conductivity
- Ultra low deflection force
- High thermal conductivity
- High tack surface reduces contact resistance
- “A” version offers high strength acrylic PSA for permanent attachment
- UL recognized V-0 flammability
RoHS compliant

Typical Applications:

- Telecommunications equipment
- Consumer electronics
- Automotive electronics (ECUs)
- LEDs, lighting
- Power conversion
- Desktop computers, laptops, servers
- Handheld devices
- Memory modules
- Vibration dampening

Product Information

THERM-A-GAP PAD 30

THERM-A-GAP PAD 30			
Typical Properties†		PAD 30	Test Method
Physical	Color	Blue	Visual
	Carrier Options: G = Woven glass - no pressure sensitive adhesive (PSA) A = Aluminum foil - with PSA PN = PEN film KT = Thermally enhanced polyimide None = No letter suffix	PAD30G PAD30A PAD30PN PAD30KT PAD30	--
	Standard Thicknesses*, in. (mm)	0.020 – 0.120 (0.50 – 3.0)	ASTM D374
	Specific Gravity	2.9	ASTM D792
	Hardness, Shore 00	38	ASTM D2240
	Percent Deflection @ Various Pressures** (0.120 in thick sample) @ 5 psi (34 kPa) @ 10 psi (69 kPa) @ 25 psi (172 kPa) @ 50 psi (345 kPa)	% Deflected 25 33 43 51	ASTM C165 MOD (0.125 in "G" Carrier, 0.50 in dia. probe, 0.025 in/min rate)
Thermal	Operating Temperature Range, °F (°C)	-67 to 392 (-55 to 200)	Chomerics
	Thermal Conductivity, W/m-K	3.2	ASTM D5470
	Thermal Impedance, °C-in ² /W (°C-cm ² /W) @ 10 psi, @ 0.04 in. (1mm) thick, "G" version	0.6 (3.9)	ASTM D5470
	Heat Capacity, J/g-K	1	ASTM E1269
	Coefficient of Thermal Expansion, ppm/K	150	ASTM E831
Electrical	Dielectric Strength, VAC/mil (KVAC/mm)	152 (6.7)	ASTM D149
	Volume Resistivity, ohm-cm	10 ¹³	ASTM D257
	Dielectric Constant @ 1,000 kHz	8.0	ASTM D150
	Dissipation Factor @ 1,000 kHz	0.009	Chomerics
Regulatory	Flammability Rating (See UL File E140244 for Details)	V-0	UL 94
	RoHS Compliant	Yes	Chomerics Certification
	Outgassing, % TML (% CVCM)	0.13 (0.03)	ASTM E595
	Shelf Life, months from date of shipment (Aluminum foil)	36 (18)	Chomerics
	Storage Conditions, °F (°C) @ 50% Relative Humidity	50 to 90 (10 to 32)	Chomerics

† Typical properties: these are not to be construed as specifications.